

捷多邦,专业PCB打样工厂,24小时加急出货

PRODUCT SPECIFICATION

PE83336 Military Operating Temperature Range

Product Description

Peregrine's PE83336 is a high performance integer-N PLL capable of frequency synthesis up to 3.0 GHz. The superior phase noise performance of the PE83336 makes it ideal for rugged military environments including: radio handsets, radar, avionics, missiles, etc.

The PE83336 features a 10/11 dual modulus prescaler, counters and a phase comparator as shown in Figure 1. Counter values are programmable through either a serial or parallel interface and can also be directly hard wired.

Fabricated in Peregrine's patented UTSi[®] (Ultra Thin Silicon) CMOS technology, the PE83336, while optimized for stringent military environments, offers excellent RF performance together with the economy and integration of conventional CMOS.

3.0 GHz Integer-N PLL for Low **Phase Noise Applications**

Features

- 3.0 GHz operation
- ÷10/11 dual modulus prescaler
- Internal phase detector
- Serial, parallel or hardwired programmable
- Ultra-low phase noise
- Available in 44-lead CQFJ





Figure 2. Pin Configuration



44-lead CQFJ

Table	1.	Pin	Des	crip	tions
				P	

Pin No. (44-lead CQFJ)	Pin Name	Interface Mode	Туре	Description
1	V _{DD}	ALL	(Note 1)	Power supply input. Input may range from 2.85 V to 3.15 V. Bypassing recommended.
2	R₀	Direct	Input	R Counter bit0 (LSB).
3	R ₁	Direct	Input	R Counter bit1.
4	R ₂	Direct	Input	R Counter bit2.
5	R ₃	Direct	Input	R Counter bit3.
6	GND	ALL	(Note 1)	Ground.
7	7 D ₀		Input	Parallel data bus bit0 (LSB).
1	Mo	Direct	Input	M Counter bit0 (LSB).
0	D ₁	Parallel	Input	Parallel data bus bit1.
0	M ₁	Direct	Input	M Counter bit1.
0	D ₂	Parallel	Input	Parallel data bus bit2.
9	M ₂	Direct	Input	M Counter bit2.
10	D ₃	Parallel	Input	Parallel data bus bit3.
10	M ₃	Direct	Input	M Counter bit3.
11	V _{DD}	ALL	(Note 1)	Same as pin 1.
12	V _{DD}	ALL	(Note 1)	Same as pin 1.
13	S WR	Serial	Input	Serial load enable input. While S WR is "low". Sdata can be serially clocked. Primary

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Pin No. (44-lead CQFJ)	Pin Name	Interface Mode	Туре	Description					
				register data are transferred to the secondary register on S_WR or Hop_WR rising edge.					
	D ₄	Parallel	Input	Parallel data bus bit4					
	M ₄	Direct	Input	M Counter bit4					
	Sdata	Serial	Input	Binary serial data input. Input data entered MSB first.					
14	D ₅	Parallel	Input	Parallel data bus bit5.					
	M ₅	Direct	Input	M Counter bit5.					
	Sclk	Serial	Input	Serial clock input. Sdata is clocked serially into the 20-bit primary register (E_WR "low") or the 8-bit enhancement register (E_WR "high") on the rising edge of Sclk.					
15	D ₆	Parallel	Input	Parallel data bus bit6.					
	M ₆	Direct	Input	M Counter bit6.					
	FSELS	Serial	Input	Selects contents of primary register (FSELS=1) or secondary register (FSELS=0) for programming of internal counters while in Serial Interface Mode.					
16	D ₇	Parallel	Input	Parallel data bus bit7 (MSB).					
	Pre_en	Direct	t Input Prescaler enable, active "low". When "high", F _{in} bypasses the prescaler.						
17	GND	ALL		Ground.					
18	FSELP	Parallel	Input	Selects contents of primary register (FSELP=1) or secondary register (FSELP=0) for programming of internal counters while in Parallel Interface Mode.					
	A ₀	Direct	Input	A Counter bit0 (LSB).					
E WR		Serial	Input	Enhancement register write enable. While E_WR is "high", Sdata can be serially clocked into the enhancement register on the rising edge of Sclk.					
19		Parallel	Input	Enhancement register write. D[7:0] are latched into the enhancement register on the rising edge of E_WR.					
	A ₁	Direct	Input	A Counter bit1.					
20	M2_WR	Parallel	Input	M2 write. D[3:0] are latched into the primary register (R[5:4], M[8:7]) on the rising edge of M2_WR.					
	A ₂	Direct	Input	A Counter bit2.					
21	Smode	Serial, Parallel	Input	Selects serial bus interface mode (Bmode=0, Smode=1) or Parallel Interface Mode (Bmode=0, Smode=0).					
	A ₃	Direct	Input	A Counter bit3 (MSB).					
22	Bmode	ALL	Input	Selects direct interface mode (Bmode=1).					
23	V _{DD}	ALL	(Note 1)	Same as pin 1.					
24	M1_WR	Parallel	Input	M1 write. D[7:0] are latched into the primary register (Pre_en, M[6:0]) on the rising edge of M1_WR.					
25	A_WR	Parallel	Input	A write. D[7:0] are latched into the primary register (R[3:0], A[3:0]) on the rising edge of A_WR.					
26	Hop_WR	Serial, Parallel	Input	Hop write. The contents of the primary register are latched into the secondary register on the rising edge of Hop_WR.					
27	F _{in}	ALL	Input	Prescaler input from the VCO. 3.0 GHz max frequency.					
28	F _{in}	ALL	Input	Prescaler complementary input. A bypass capacitor should be placed as close as possible to this pin and be connected in series with a 50 Ω resistor directly to the ground plane.					
29	GND	ALL		Ground.					



Pin No. (44-lead CQFJ)	Pin Name	Interface Mode	Туре	Description			
30	fp	ALL	Output	Monitor pin for main divider output. Switching activity can be disabled through enhancement register programming or by floating or grounding V_{DD} pin 31.			
31	V _{DD} -f _p	ALL	(Note 1)	V_{DD} for $f_{\text{p}}.$ Can be left floating or connected to GND to disable the f_{p} output.			
32	Dout	Serial, Parallel	Output	Data Out. The MSEL signal and the raw prescaler output are available on Dout through enhancement register programming.			
33	V _{DD}	ALL	(Note 1)	Same as pin 1.			
34	Cext	ALL	Logical "NAND" of PD_U and PD_D terminated through an on chip, Connecting Cext to an external capacitor will low pass filter the inpu amplifier used for driving LD.				
35	V _{DD}	ALL	(Note 1)	Same as pin 1.			
36	PD_D	ALL	Output	PD_D is pulse down when f_p leads f_c .			
37	PD_U	ALL		PD_U is pulse down when f_c leads f_p .			
38	V_{DD} -f _c	ALL	(Note 1)	V_{DD} for f_{c} can be left floating or connected to GND to disable the f_{c} output.			
39	f _c	ALL	Output	Monitor pin for reference divider output. Switching activity can be disabled through enhancement register programming or by floating or grounding V_{DD} pin 38.			
40	GND	ALL		Ground.			
41	GND	ALL		Ground.			
42	f _r	ALL	Input	Reference frequency input.			
43	LD	ALL	Output	Lock detect and open drain logical inversion of CEXT. When the loop is in lock, LD is high impedance, otherwise LD is a logic low ("0").			
44	Enh	Serial, Parallel	Input	Enhancement mode. When asserted low ("0"), enhancement register bits are functional.			
N/A	NC	ALL		No connection.			

Note 1: All V_{DD} pins are connected by diodes and must be supplied with the same positive voltage level.

 V_{DD} - f_p and V_{DD} - f_p are used to power the f_p and f_c outputs and can alternatively be left floating or connected to GND to disable the f_p and f_c outputs.

Note 2: All digital input pins have 70 k Ω pull-down resistors to ground.



Table 2. Absolute Maximum Ratings

Symbol	Parameter/Conditions	Min	Max	Units
V _{DD}	Supply voltage	-0.3	4.0	V
VI	Voltage on any input	-0.3	V _{DD} + 0.3	V
L.	DC into any input	-10	+10	mA
Ιo	DC into any output	-10	+10	mA
T _{stg}	Storage temperature range	-65	150	°C

Table 3. Operating Ratings

Symbol	Parameter/Conditions	Min	Max	Units
V _{DD}	Supply voltage	2.85	3.15	V
T _A	Operating ambient temperature range	-55	125	°C

Table 4. ESD Ratings

Symbol	Parameter/Conditions	Level	Units
V _{ESD}	ESD voltage (Human Body Model)	1000	V

Note 1: Periodically sampled, not 100% tested. Tested per MIL-STD-883, M3015 C2

Electrostatic Discharge (ESD) Precautions

When handling this *UTSi* [®] device, observe the same precautions that you would use with other ESD-sensitive devices. Although this device contains circuitry to protect it from damage due to ESD, precautions should be taken to avoid exceeding the rating specified in Table 4.

Latch-Up Avoidance

Unlike conventional CMOS devices, *UTSi* [®] CMOS devices are immune to latch-up.



Table 5. DC Characteristics

 V_{DD} = 3.0 V, -55° C ≤ T_A ≤ 125° C, unless otherwise specified

Symbol	Parameter	Conditions	Min	Тур	Max	Units
I _{DD}	Operational supply current;	V _{DD} = 2.85 to 3.15 V				
	Prescaler disabled			10		mA
	Prescaler enabled			20	28	mA
Digital Inputs:	: All except f _r , R₀, F _{in} , F _{in}					
V _{IH}	High level input voltage	V _{DD} = 2.85 to 3.15 V	$0.7 \times V_{DD}$			V
VIL	Low level input voltage	V _{DD} = 2.85 to 3.15 V			$0.3 \times V_{DD}$	V
I _{IH}	High level input current	V _{IH} = V _{DD} = 3.15 V			+70	μA
IIL	Low level input current	V _{IL} = 0, V _{DD} = 3.15 V	-1			μA
Reference Div	rider input: fr					
I _{IHR}	High level input current	V _{IH} = V _{DD} = 3.15 V			+100	μA
I _{ILR}	Low level input current	V _{IL} = 0, V _{DD} = 3.15 V	-100			μA
R0 Input (Pull-	-up Resistor): R₀					
I _{IHRO}	High level input current	V _{IH} = V _{DD} = 3.15 V			+70	μA
I _{ILRO}	Low level input current	V _{IL} = 0, V _{DD} = 3.15 V	-5			μA
Counter and p	phase detector outputs: f _c , f _p , PD_D, PD_U					
V _{OLD}	Output voltage LOW	I _{out} = 6mA			0.4	V
V _{OHD}	Output voltage HIGH	I _{out} = -3mA	V _{DD} - 0.4			V
Lock detect of	utputs: Cext, LD					
V _{OLC}	Output voltage LOW, Cext	I _{out} = 100uA			0.4	V
V _{OHC}	Output voltage HIGH, Cext	I _{out} = -100uA	V _{DD} - 0.4			V
V _{OLLD}	Output voltage LOW, LD	I _{out} = 6mA			0.4	V



Table 6. AC Characteristics

 V_{DD} = 3.0 V, -55° C ≤ T_A ≤ 125° C, unless otherwise specified

	Symbol	Parameter	Conditions	Min	Тур	Max	Units	
$ \begin{array}{c c_x} & Serial clock HiGH time & 10 MHz \\ \hline t_{c_{ht}} & Serial clock HIGH time & 30 & ns \\ \hline t_{c_{ht}} & Serial clock LOW time & 30 & ns \\ \hline t_{c_{ht}} & Serial clock LOW time & 30 & ns \\ \hline t_{c_{ht}} & Serial clock LOW time & ns & 30 & ns \\ \hline t_{c_{ht}} & Serial clock LOW time & ns & 30 & ns \\ \hline t_{c_{ht}} & Serial clock LOW time & ns & 10 & ns \\ \hline t_{c_{ht}} & Serial clock LOW time & ns & 10 & ns \\ \hline t_{c_{ht}} & Serial clock LOW time & ns & ns & 10 & ns \\ \hline t_{c_{ht}} & S{t_{ht}} MR, M1_{WR}, M2_{WR}, A_{WR}, E_{WR} raising edge & 10 & 10 & ns \\ \hline t_{wr} & S{t_{ht}} MR, M1_{WR}, M2_{WR}, A_{WR}, E_{WR} raising edge & 30 & ns & ns \\ \hline t_{wr} & S{t_{ht}} Sing edge to SWR raing edge & SWR, M1_{WR}, \\ M2_{WR}, M2_{WR}, M1_{WR}, M2_{WR}, A_{WR}, H1_{WR}, M2_{WR}, A_{WR} raing edge & 30 & ns & ns \\ \hline t_{wr} & S{t_{ht}} Halling edge to Nop_{_{WR}} raing edge & 30 & ns & ns \\ \hline t_{wr} & S{t_{H}} Halling edge to Skir raing edge & 0 & c_{_{1}} 21 pf & 8 (Note 5) & ns & ns \\ \hline t_{wr} & S{WR} falling edge to Skir raing edge & C_{_{1}} 21 pf & 8 (Note 5) & ns & ns \\ \hline t_{wr} & S{WR} training not Skir raing edge & C_{_{1}} 21 pf & 8 (Note 5) & ns & n$	Control Inte	rface and Latches (see Figures 3, 4, 5)	•					
Grait Serial clock HGH time Image 30 m ms tmail Serial clock LGW time Image 30 Image ms tmail Statis actual time after Scik rising edge 10 10 Image ms the total mode time after Scik rising edge 10 10 Image ms the total mode time after Scik rising edge edge, DT/01 hold time to M1_WR_A_WR_A_WR_E_WR_A_WR_E_WR_Publies width 30 Image ms the total mode time after Scik rising edge edge, DT/01 hold time to M1_WR_A_WR_A_WR_E_WR_A_WR_EWR rising edge 30 Image ms the total mode time after Scik rising edge edge, DT/01 hold time to M2_WR_A_WR failing edge to Scik rising edge edge, DT/01 hold time to edge to S_WR failing edge to Scik rising edge 30 Image ms the total mode by after Fin rising edge C_c = 12 pf Image 8 (Note 5) ms thano MSE L data out delay after Fin rising edge C_c = 12 pf Image 8 (Note 5) ms thano MSE L data out delay after Fin rising edge C_c = 12 pf Image Image Image thano MSE L data out delay after Fin rising edge	f _{Clk}	Serial data clock frequency				10	MHz	
LaxSerial cock LOW time30nstsauSdata set-up time after Scik rising edge. [J:0] set-up into to M1_WR, M2_WR, A_WR, E_WR nising edge1010nsthreaSdata sol-up time after Scik rising edge. [J:0] to thime to M1_WR, M2_WR, A_WR, E_WR nising edge1010nsthwaS_WR, M1_WR, M2_WR, A_WR, E_WR pulse width301010nstowaS_WR, M1_WR, M2_WR, A_WR, E_WR pulse width301010nstowaS_WR, M1_WR, M2_WR, A_WR, E_WR pulse width3010nstowaS_WR failing edge to S_WR, M1_WR, Q_WR, A_WR rising edge3010nsthreaScik rising edge. S_WR, M1_WR, A_WR rising edge3010nsthreaS_WR failing edge to S_WR, M1_WR, A_WR rising edge3010nsthreaScik rising edgeC_ = 12 pf3010nsthreaMSEL data out delay after Fin rising edgeC_ = 12 pf108 (Note 5)nsMain DividerMSEL data out delay after Fin rising edge5003000MH2Fr.Operating frequency5003000MH2PineInput level rangeExternal AC coupling 85°C < T_A \$ 125°C	t _{CIkH}	Serial clock HIGH time		30			ns	
	t _{CIkL}	Serial clock LOW time		30			ns	
betterSdate hold time after Scikt ning edge. DP.0] hold time to M_WR, M2_WR, A_WR, E_WR ning edge101010101010S_WR, M1_WR, M2_WR, A_WR, E_WR pulse width30nstomaScik ring edge to S_WR ring edge S_WR, M1_WR, M2_WR, A_WR falling edge to E_WR transition30nstowaScik raling edge to E_WR transition30nstowacS_WR falling edge to SL vieng edge. Hop_WR falling edge to S_WR, M1_WR, M2_WR, A_WR ning edge30nstowacE_WR transition to Scik rising edgeC_t = 12 pf30nstowacMSEL data out delay after Fin rising edgeC_t = 12 pf300MRMRtowacMSEL data out delay after Fin rising edge500300MRPrinInput level rangeExternal AC coupling 85°C < T_A \$ 125°C	t _{DSU}	Sdata set-up time after Sclk rising edge, D[7:0] set-up time to M1_WR, M2_WR, A_WR, E_WR rising edge		10			ns	
$ \begin{array}{ c c c c } \hline here & S_WR, M_1_WR, M_2_WR, A_WR, F_WR pulse width & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & $	t _{DHLD}	Sdata hold time after Sclk rising edge, D[7:0] hold time to M1_WR, M2_WR, A_WR, E_WR rising edge		10			ns	
Lower Normal Wind W	t _{PW}	S_WR, M1_WR, M2_WR, A_WR, E_WR pulse width		30			ns	
L_{cc} Sck falling edge to E_WR transitionNo30NoNo M_{MC} S_{MR} falling edge to Sck rising edge. Hop_WR falling edge to S_WR, M1_WR, AWR, AWR rising edge303030No L_{cc} E_{MR} transition to Sck rising edge $C_{L} = 12 \text{pf}$ 30100NoNo M_{MDC} $MSEL$ data out delay after Fin rising edge $C_{L} = 12 \text{pf}$ 3001008 (Note 5)Ns M_{MDC} $MSEL$ data out delay after Fin rising edge $C_{L} = 12 \text{pf}$ 503000MHz M_{MDC} $MSEL$ data out delay after Fin rising edge $L_{L} = 12 \text{pf}$ 300 MHZ M_{MDC} $MSEL$ data out delay after Fin rising edge $L_{L} = 12 \text{pf}$ 300 MHZ M_{MDC} $Mput level rangeSSC < T_A \leq 125 \text{C}SSC < T_A \leq 125 \text{C}SSC < T_A \leq 125 \text{C}M_{Pr}Mput level rangeSSC < T_A \leq 125 \text{C}SSC < T_A \leq 125 \text{C}SSC < T_A \leq 125 \text{C}SSC < T_A \leq 125 \text{C}P_{Fin}Nput level rangeExternal AC couplingSSC < T_A \leq 125 \text{C}SSC < T_$	t _{CWR}	Sclk rising edge to S_WR rising edge. S_WR, M1_WR, M2_WR, A_WR falling edge to Hop_WR rising edge		30			ns	
bwnc edge to S_WR, M1_WR, M2_WR, A_WR rising edge303010ns t_{tc} t_{wc} by Kransition to Scik rising edge $<$ 30 $<$ $<$ ns t_{wco} MSEL data out delay after Fin rising edge $C_{L} = 12 \text{ pf}$ 300 d Note 5) ns Main DiviturMSEL data out delay after Fin rising edge $C_{L} = 12 \text{ pf}$ 500 3000 MHz F_n Operating frequency $External AC coupling$ 500 3000 MHz F_n Input level rangeExternal AC coupling $85^{\circ}C < T_A \le 125^{\circ}C$ 50 3000 MHz P_{Em} Operating frequency $External AC coupling$ $85^{\circ}C < T_A \le 125^{\circ}C$ 300 MHz P_n Operating frequency $External AC coupling$ $85^{\circ}C < T_A \le 125^{\circ}C$ 300 MHz P_n Operating frequency $External AC coupling$ $85^{\circ}C < T_A \le 125^{\circ}C$ 300 MHz P_n Operating frequency $External AC coupling$ $85^{\circ}C < T_A \le 125^{\circ}C$ 300 MHz P_n Reference input page $External AC coupling$ $85^{\circ}C < T_A \le 125^{\circ}C$ 300 MHz P_n Input level range $External AC coupling$ $85^{\circ}C < T_A \le 125^{\circ}C$ 100 MHz P_n Reference input page $(Note 1)$ $(Note 2)$ 100 MHz P_n Reference input page $(Note 1)$ $(Note 2)$ 100 MHz P_n Reference input page $(Note 1)$ 20 MHz P_n Refere	t _{CE}	Sclk falling edge to E_WR transition		30			ns	
tccE_WR transition to Sclk rising edgeIns30InsInstuttooMSEL data out delay after Fin rising edgeC_L = 12 pfII8 (Note 5)InsMarce Luding Prescular)FinOperating frequencyExternal AC coupling 85° c < T_A ≤ 125°°	t _{wrc}	S_WR falling edge to Sclk rising edge. Hop_WR falling edge to S_WR, M1_WR, M2_WR, A_WR rising edge		30			ns	
Marcel Mar	t _{EC}	E_WR transition to Sclk rising edge		30			ns	
Main Divide: [Including Prescaler) F_{in} Operating frequencyExternal AC coupling50003000MHz P_{Fin} Input level rangeExternal AC coupling $B^{50} < T_A \le 125^{\circ C}$ 05dBmMain Divide: [Prescaler Bypassed)Main Divide: [Prescaler Bypassed)FinOperating frequency503000MHz P_{Fin} Operating frequency503000MHz P_{Fin} Input level rangeExternal AC coupling $B^{5\circ} C < T_A \le 125^{\circ C}$ 050dBmReference UReference input power50100MHzPinInput level rangeSingle ended input $B^{5\circ} C < T_A \le 125^{\circ C}$ 100MHzReference input power0503000MHzPinInput level range050100MHzPinSingle ended input $B^{5\circ} C < T_A \le 125^{\circ C}$ 100MHzPinSingle ended input $B^{5\circ} C < T_A \le 125^{\circ C}$ 100MHzPinSingle ended input $B^{5\circ} C < T_A \le 125^{\circ C}$ 100MHzPinReference input powerSingle ended input $C^{5} C < T_A \le 125^{\circ C}$ 100MHzPinReference input powerSingle ended input $C^{5} C < T_A \le 125^{\circ C}$ 20MHzPinComparison frequency(Note 1)10020MHz <td c<="" td=""><td>t_{MDO}</td><td>MSEL data out delay after Fin rising edge</td><td>C_L = 12 pf</td><td></td><td></td><td>8 (Note 5)</td><td>ns</td></td>	<td>t_{MDO}</td> <td>MSEL data out delay after Fin rising edge</td> <td>C_L = 12 pf</td> <td></td> <td></td> <td>8 (Note 5)</td> <td>ns</td>	t _{MDO}	MSEL data out delay after Fin rising edge	C _L = 12 pf			8 (Note 5)	ns
$ \begin{array}{ c c c c } \hline F_{\text{In}} & \mbox{Operating frequency} & \mbox{Input level range} & Input leve$	Main Divide	r (Including Prescaler)						
$\begin{array}{ c c c } & P_{\text{Fin}} & Input Ievel range $	F _{in}	Operating frequency		500		3000	MHz	
$ \begin{array}{ c c c c c } \hline \mbox{External AC coupling} & 0 & 0 & 5 & 0 & 0 \\ \hline \mbox{BS}^{\circ} < T_A \leq 125^{\circ} C & 1 & 0 & 0 & 0 & 0 & 0 \\ \hline \mbox{Bind Individual Sector Bypassed} & 0 & 50 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & $	P _{Fin}	Input level range	External AC coupling	-5		5	dBm	
$\begin{tabular}{ c c c c } \hline Main Divider (Prescaler Bypassed) & & & & & & & & & & & & & & & & & & &$			External AC coupling 85°C < T _A ≤ 125°C	0		5	dBm	
$ \begin{array}{c c c c c c } \hline F_{n} & Operating frequency & Input level range & External AC coupling & -5 & Input level range & Input level range & External AC coupling & 0 & 5 & dBm & BSS & C < T_A < 125 °C & Input level range & Input$	Main Divide	r (Prescaler Bypassed)		•	•			
$ \begin{array}{ c c c } P_{\text{Fin}} & \text{Input level range} & \underline{\text{External AC coupling}} & 1.5 & 1.0 & 5. & dBm \\ \hline \text{External AC coupling}} & 0 & 0 & 5. & dBm \\ \hline \text{BS}^{\circ} C < T_A \leq 125^{\circ} C & 1.0 & 1.0 & 1.0 & 1.0 & 1.0 & 1.0 & 1.0 & 1.0 & 1.0 & 1.0 & 1.0 & 1.0 & 0.0 & 1.0 & 0.$	Fin	Operating frequency		50		300	MHz	
External AC coupling $85^{\circ}C < T_A \le 125^{\circ}C$ 05dBmReference $55^{\circ}C < T_A \le 125^{\circ}C$ 005dBmReference input power(Note 1)(Note 2)100MHz f_r Operating frequency(Note 1)(Note 2)1000 P_{fr} Reference input powerSingle ended input-2100dBm V_{fr} Input sensitivityExternal AC coupling (Note 3)0.510020MHzPhase DetererInput sensitivity(Note 1)10020MHzfcComparison frequency(Note 1)10020MHzSSB Phase Vise : Output Referred (F _{in} = 1918MHz, f, = 10 MHz, f_c = THz, LBW = 70 kHz)-78(Note 4)dBc/HzPNOROutput Referred Phase Noise100 Hz Offset: V_{DD} = 3.0V, T = 25^{\circ}C-94(Note 4)dBc/Hz	P _{Fin}	Input level range	External AC coupling	-5		5	dBm	
Reference DividerfrOperating frequency(Note 1)(Note 2)100MHz P_{fr} Reference input powerSingle ended input-210dBm V_{fr} Input sensitivityExternal AC coupling (Note 3)0.50VP.PPhase Detectorf_cComparison frequency(Note 1)020MHzSSB Phase Noise : Output Referred (Fin = 1918MHz, fr = 10 MHz, fc = 1MHz, LBW = 70 kHz)PNoROutput Referred Phase Noise100 Hz Offset: VDD = 3.0V, T = 25°C-78(Note 4)dBc/HzPNoROutput Referred Phase Noise1000 Hz Offset: VDD = 3.0V, T = 25°C-94(Note 4)dBc/Hz			External AC coupling 85°C < T _A ≤ 125°C	0		5	dBm	
f_r Operating frequency(Note 1)(Note 2)100MHz P_{fr} Reference input powerSingle ended input-210dBm V_{fr} Input sensitivityExternal AC coupling (Note 3)0.50.5 $V_{P,P}$ Phase Detector f_c Comparison frequency(Note 1)20MHzSSB Phase Noise : Output Referred (F_{in} = 1918MHz, f_r = 10 MHz, f_c = 1MHz, LBW = 70 kHz)-78(Note 4)dBc/Hz PN_{OR} Output Referred Phase Noise100 Hz Offset: V_{DD} = 3.0V, T = 25°C-78(Note 4)dBc/Hz PN_{OR} Output Referred Phase Noise1000 Hz Offset: V_{DD} = 3.0V, T = 25°C-94(Note 4)dBc/Hz	Reference D	livider						
P_{fr} Reference input powerSingle ended input-210dBm V_{fr} Input sensitivityExternal AC coupling (Note 3)0.50.5 V_{P-P} Phase Detectorf_cComparison frequency(Note 1)1020MHzSSB Phase : Output Referred (F_in = 1918MHz, f_r = 10 MHz, f_c = TMHz, LBW = 70 kHz)PN_{OR}Output Referred Phase Noise100 Hz Offset: V_{DD} = 3.0V, T = 25°C-78(Note 4)dBc/HzPN_{OR}Output Referred Phase Noise1000 Hz Offset: V_{DD} = 3.0V, T = 25°C-94(Note 4)dBc/Hz	fr	Operating frequency	(Note 1)	(Note 2)		100	MHz	
V_{fr} Input sensitivityExternal AC coupling (Note 3)0.5Image: Note of the sensitivityPhase Detectorf_cComparison frequency(Note 1)Image: Note of the sensitivityMHzSSB Phase : Output Referred (F _{in} = 1918MHz, f_r = 10 MHz, f_c = 1WHz, LBW = 70 kHz)PNoROutput Referred Phase Noise100 Hz Offset: VDD = 3.0V, T = 25°C-78(Note 4)dBc/HzPNoROutput Referred Phase Noise1000 Hz Offset: VDD = 3.0V, T = 25°C-94(Note 4)dBc/Hz	P _{fr}	Reference input power	Single ended input	-2		10	dBm	
Phase Detector f_c Comparison frequency(Note 1)20MHzSSB Phase Noise : Output Referred ($F_{in} = 1918$ MHz, $f_r = 10$ MHz, $f_c = 1$ MHz, LBW = 70 kHz) PN_{OR} Output Referred Phase Noise100 Hz Offset: V_{DD} $= 3.0V, T = 25^{\circ}C$ -78(Note 4)dBc/Hz PN_{OR} Output Referred Phase Noise1000 Hz Offset: V_{DD} $= 3.0V, T = 25^{\circ}C$ -94(Note 4)dBc/Hz	V _{fr}	Input sensitivity	External AC coupling (Note 3)	0.5			V_{P-P}	
f_c Comparison frequency(Note 1)20MHzSSB Phase Noise : Output Referred (F_{in} = 1918MHz, f_r = 10 MHz, f_c = 1/2 HHz, LBW = 70 kHz)PNOROutput Referred Phase Noise100 Hz Offset: VDD = 3.0V, T = 25°C-78(Note 4)dBc/HzPNOROutput Referred Phase Noise1000 Hz Offset: VDD = 3.0V, T = 25°C-94(Note 4)dBc/Hz	Phase Dete	ctor						
SSB Phase Noise : Output Referred (F_{in} = 1918MHz, f_r = 10 MHz, f_c = 1/2 LBW = 70 kHz)PNOROutput Referred Phase Noise100 Hz Offset: V_{DD} = 3.0V, T = 25°C-78(Note 4)dBc/HzPNOROutput Referred Phase Noise1000 Hz Offset: V_{DD} = 3.0V, T = 25°C-94(Note 4)dBc/Hz	fc	Comparison frequency	(Note 1)			20	MHz	
PN_{OR} Output Referred Phase Noise100 Hz Offset: V_{DD} -78(Note 4)dBc/Hz PN_{OR} Output Referred Phase Noise1000 Hz Offset: V_{DD} -94(Note 4)dBc/Hz PN_{OR} Output Referred Phase Noise1000 Hz Offset: V_{DD} -94(Note 4)dBc/Hz	SSB Phase	Noise : Output Referred (F _{in} = 1918MHz, f _r = 10 MHz, f _c = 1	MHz, LBW = 70 kHz)					
PN_{OR} Output Referred Phase Noise1000 Hz Offset: V_{DD} -94(Note 4)dBc/Hz $= 3.0V, T = 25^{\circ}C$	PN _{OR}	Output Referred Phase Noise	100 Hz Offset: V _{DD} = 3.0V, T = 25°C		-78	(Note 4)	dBc/Hz	
	PN _{OR}	Output Referred Phase Noise	1000 Hz Offset: V _{DD} = 3.0V, T = 25°C		-94	(Note 4)	dBc/Hz	

Note 1: Parameter is guaranteed through characterization only and is not tested.

Note 2: Running at low frequencies (< 10 MHz sinewave), the device will still be functional but may cause phase noise degradation. Inserting a lownoise amplifier to square up the edges is recommended at lower input frequencies.

Note 3: CMOS logic levels may be used if DC coupled. For optimum phase noise performance, the reference input falling edge rate should be faster than 80mV/ns.

Note 4: All devices are screened to phase noise limits listed in Table 7. The magnitude of the tester uncertainty precludes testing phase noise as part of qualification testing. These parameters are also exempt from PDA requirements.

Note 5: Parameter is tested using 100pF load capacitance and is guaranteed through characterization only. Typical test delay is 12nS.



Table 7. Phase Noise Test

Test name	Conditions	Max	Units
Phase Noise	100 Hz Offset	-80	dBc/Hz
	1000 Hz Offset	-87	dBc/Hz

Functional Description

The *PE83336* consists of a prescaler, counters, a phase detector and control logic. The dual modulus prescaler divides the VCO frequency by either 10 or 11, depending on the value of the modulus select. Counters "R" and "M" divide the reference and prescaler output, respectively, by integer values stored in a 20-bit register. An additional counter

("A") is used in the modulus select logic. The phasefrequency detector generates up and down frequency control signals. The control logic includes a selectable chip interface. Data can be written via serial bus, parallel bus, or hardwired direct to the pins. There are also various operational and test modes and lock detect.

Figure 3. Functional Block Diagram





Main Counter Chain

The main counter chain divides the RF input frequency, F_{in} , by an integer derived from the user defined values in the "M" and "A" counters. It is composed of the 10/11 dual modulus prescaler, modulus select logic, and 9-bit M counter. Setting Pre_en "low" enables the 10/11 prescaler. Setting Pre_en "high" allows F_{in} to bypass the prescaler and powers down the prescaler.

The output from the main counter chain, f_p , is related to the VCO frequency, F_{in} , by the following equation:

 $f_p = F_{in} / [10 \times (M + 1) + A]$ (1) where $A \le M + 1, 1 \le M \le 511$

When the loop is locked, F_{in} is related to the reference frequency, f_r , by the following equation:

$$F_{in} = [10 \times (M + 1) + A] \times (f_r / (R+1))$$
(2)
where $A \le M + 1, 1 \le M \le 511$

A consequence of the upper limit on A is that F_{in} must be greater than or equal to 90 x (f_r / (R+1)) to obtain contiguous channels. Programming the M Counter with the minimum value of "1" will result in a minimum M Counter divide ratio of "2".

When the prescaler is bypassed, the equation becomes:

$$F_{in} = (M + 1) \times (f_r / (R+1))$$
(3)
where $1 \le M \le 511$

In Direct Interface Mode, main counter inputs M_7 and M_8 are internally forced low.

Reference Counter

The reference counter chain divides the reference frequency, f_r , down to the phase detector comparison frequency, f_c .

The output frequency of the 6-bit R Counter is related to the reference frequency by the following equation:

 $f_c = f_r / (R + 1)$ where $0 \le R \le 63$ (4)

Note that programming R equal to "0" will pass the reference frequency, f_r , directly to the phase detector.

In Direct Interface Mode, R Counter inputs R_4 and R_5 are internally forced low ("0").

Register Programming

Parallel Interface Mode

Parallel Interface Mode is selected by setting the Bmode input "low" and the Smode input "low".

Parallel input data, D[7:0], are latched in a parallel fashion into one of three, 8-bit primary register sections on the rising edge of M1_WR, M2_WR, or A_WR per the mapping shown in Table 7 on page 10. The contents of the primary register are transferred into a secondary register on the rising edge of Hop_WR according to the timing diagram shown in Figure 4. Data are transferred to the counters as shown in Table 7 on page 10.

The secondary register acts as a buffer to allow rapid changes to the VCO frequency. This double buffering for "ping-pong" counter control is programmed via the FSELP input. When FSELP is "high", the primary register contents set the counter inputs. When FSELP is "low", the secondary register contents are utilized.

Parallel input data, D[7:0], are latched into the enhancement register on the rising edge of E_WR according to the timing diagram shown in Figure 4. This data provides control bits as shown in Table 8 on page 10 with bit functionality enabled by asserting the Enh input "low".

Serial Interface Mode

Serial Interface Mode is selected by setting the Bmode input "low" and the Smode input "high".

While the E_WR input is "low" and the S_WR input is "low", serial input data (Sdata input), B_0 to B_{19} , are clocked serially into the primary register on the rising edge of Sclk, MSB (B_0) first. The contents from the primary register are transferred into the secondary register on the rising edge of either S_WR or Hop_WR according to the timing diagram shown in Figures 4-5. Data are transferred to the counters as shown in Table 7 on page 10.

The double buffering provided by the primary and secondary registers allows for "ping-pong" counter control using the FSELS input. When FSELS is "high", the primary register contents set the counter inputs. When FSELS is "low", the secondary register contents are utilized.

While the E_WR input is "high" and the S_WR input is "low", serial input data (Sdata input), B_0 to B_7 , are clocked serially into the enhancement register on the rising edge of Sclk, MSB (B_0) first. The enhancement register is double buffered to prevent



inadvertent control changes during serial loading, with buffer capture of the serially entered data performed on the falling edge of E_WR according to the timing diagram shown in Figure 5. After the falling edge of E_WR, the data provide control bits as shown in Table 8 with bit functionality enabled by asserting the Enh input "low".

Direct Interface Mode

Direct Interface Mode is selected by setting the Bmode input "high".

Counter control bits are set directly at the pins as shown in Table 7. In Direct Interface Mode, main counter inputs M_7 and M_8 , and R Counter inputs R_4 and R_5 are internally forced low ("0").

Interface Mode	Enh	Bmode	Smode	R₅	R₄	M ₈	M ₇	Pre_en	M ₆	M₅	M4	M ₃	M ₂	M ₁	Mo	R ₃	R ₂	R ₁	R₀	A ₃	A ₂	A 1	A ₀
Parallel	1	0	0	M2_V	I2_WR rising edge load M1_WR rising edge load							A_WR rising edge load											
				D_3	D_2	D ₁	D_0	D ₇	D_6	D_5	D_4	D_3	D_2	D ₁	D_0	D ₇	D_6	D_5	D_4	D_3	D_2	D_1	D ₀
Serial*	1	0	1	B ₀	B ₁	B ₂	B ₃	B ₄	B ₅	B ₆	B ₇	B ₈	B ₉	B ₁₀	B ₁₁	B ₁₂	B ₁₃	B ₁₄	B ₁₅	B ₁₆	B ₁₇	B ₁₈	B ₁₉
Direct	1	1	х	0	0	0	0	Pre_en	M ₆	M_5	M_4	M_3	M_2	M ₁	M ₀	R ₃	R_2	R_1	R ₀	A ₃	A ₂	A ₁	A ₀

Table 8. Primary Register Programming

*Serial data clocked serially on Sclk rising edge while E_WR "low" and captured in secondary register on S_WR rising edge.

MSB (first in)

(last in) LSB

Table 9. Enhancement Register Programming

Interface Mode	Enh	Bmode	Smode	Reserved	Reserved	Reserved	Power down	Counter Ioad	MSEL output	Prescaler output	$f_c, f_p OE$
Parallel	0	x	0				E_WR risin	g edge load			
Parallel	0	~	0	D ₇	D ₆	D_5	D ₄	D ₃	D ₂	D ₁	D ₀
Serial*	0	х	1	B ₀	B ₁	B ₂	B ₃	B ₄	B ₅	B ₆	B ₇

*Serial data clocked serially on Sclk rising edge while E_WR "high" and captured in the double buffer on E_WR falling edge.



(last in) LSB







Figure 5. Serial Interface Mode Timing Diagram







Enhancement Register

The functions of the enhancement register bits are shown below with all bits active "high".

Table 10. Enhancement Register Bit Functionality

Bit Function		Description		
Bit 0	Reserved**			
Bit 1	Reserved**			
Bit 2	Reserved**			
Bit 3	Power down	Power down of all functions except programming interface.		
Bit 4	Counter load	Immediate and continuous load of counter programming as directed by the Bmode and Smode inputs.		
Bit 5	MSEL output	Drives the internal dual modulus prescaler modulus select (MSEL) onto the Dout output.		
Bit 6	Prescaler output	Drives the raw internal prescaler output onto the Dout output.		
Bit 7	f _p , f _c OE	f_{p}, f_{c} outputs disabled.		

** Program to 0

Phase Detector

The phase detector is triggered by rising edges from the main Counter (f_p) and the reference counter (f_c). It has two outputs, PD_U, and PD_D. If the divided VCO leads the divided reference in phase or frequency (f_p leads f_c), PD_D pulses "low". If the divided reference leads the divided VCO in phase or frequency (f_c leads f_p), PD_U pulses "low". The width of either pulse is directly proportional to phase offset between the two input signals, f_p and f_c .

The phase detector gain is equal to 2.7 V / 2 π , which numerically yields 0.43 V / radian.

PD_U and PD_D drive an active loop filter which controls the VCO tune voltage. PD_U pulses result in an increase in VCO frequency; PD_D pulses result in a decrease in VCO frequency (for a positive Kv VCO).

A lock detect output, LD is also provided, via the pin Cext. Cext is the logical "NAND" of PD_U and PD_D waveforms, which is driven through a series 2 kohm resistor. Connecting Cext to an external shunt capacitor provides low pass filtering of this signal. Cext also drives the input of an internal inverting comparator with an open drain output. Thus LD is an "AND" function of PD_U and PD_D.



Figure 6. Package Drawing

44-lead CQFJ



All dimensions are in mils

Table 11. Ordering Information

Order Code	Part Marking	Description	Package	Shipping Method	Product Status
83336-21	PE83336	Packaged Part	44-lead CQFJ	26 units / Tube	
83336-22	PE83336	Packaged Part	44-lead CQFJ	500 units / T&R	
83336-00	PE83336EK	CQFJ Evaluation Board with Software	44-lead CQFJ	1 / Box	



Sales Offices

United States

Peregrine Semiconductor Corp.

6175 Nancy Ridge Drive San Diego, CA 92121 Tel 1-858-455-0660 Fax 1-858-455-0770

Japan

Peregrine Semiconductor K.K. 5A-5, 5F Imperial Tower 1-1-1 Uchisaiwaicho, Chiyoda-ku, Tokyo, Japan 100-011 Tel. 011-81-3-3502-5211 Fax. 011-81-3-3502-5213

Europe

Peregrine Semiconductor Europe

Aix-En-Provence Office Parc Club du Golf, bat 9 13856 Aix-En-Provence Cedex 3 France Tel 011-33-0-4-4239-3360 Fax 011-33-0-4-4239-7227

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